

#10/Amend E  
Doc. 104 (OE)

Ator  
7/9/02

TECHNOLOGY CENTER 2690

JUL - 1 2002

RECEIVED

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant : Ted A. Loxley  
Serial No. : 09/490,162  
Filed : January 22, 2000

For: PROCESS AND APPARATUS FOR CLEANING SILICON WAFERS

Examiner : V. Simkovic

Group Art Unit : 2812 Confirmation No. 681690

Box AF  
Assistant Commissioner for Patents  
Washington, D.C. 20231

please enter AS

please note page 4

AMENDMENT AFTER FINAL REJECTION  
Request for Correction (37CFR1.105)

Sir:

In connection with the final Office action of October 19, 2001, now on appeal, please amend the above-identified application as follows:

Cancel claims 18, 7, 19, 20, 21, 25, 28, 29 and 31 and rewrite as follows:

| -- ~~18~~. (Amended) In a process of the character described for fabrication of microelectronic devices on silicon wafers wherein microcircuits are formed on the front face of a wafer by a plurality of layering, patterning, doping and heating operations and the wafer is wetted and repeatedly subjected to cleaning, rinsing and drying operations to remove contaminants, the improvement wherein said front face of the process wafer is